
AMORPHOUS SILICON CARBIDE REAR-SIDE PASSIVATION AND REFLECTOR LAYER STACKS FOR MJ SPACE SOLAR CELLS BASED ON GE SUBSTRATES



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Motivation

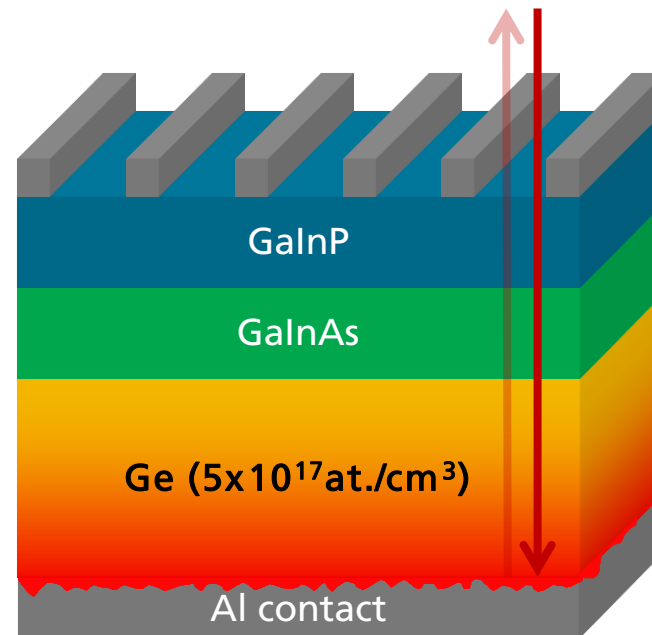
III-V Multi-Junction Space Solar Cell

Trends in III-V space solar cells

- Additional junctions
 - increase efficiency
- Thinner Ge cells
 - reduce weight

Demands for Ge substrate

- Improved diffusion lengths
- Surface passivation

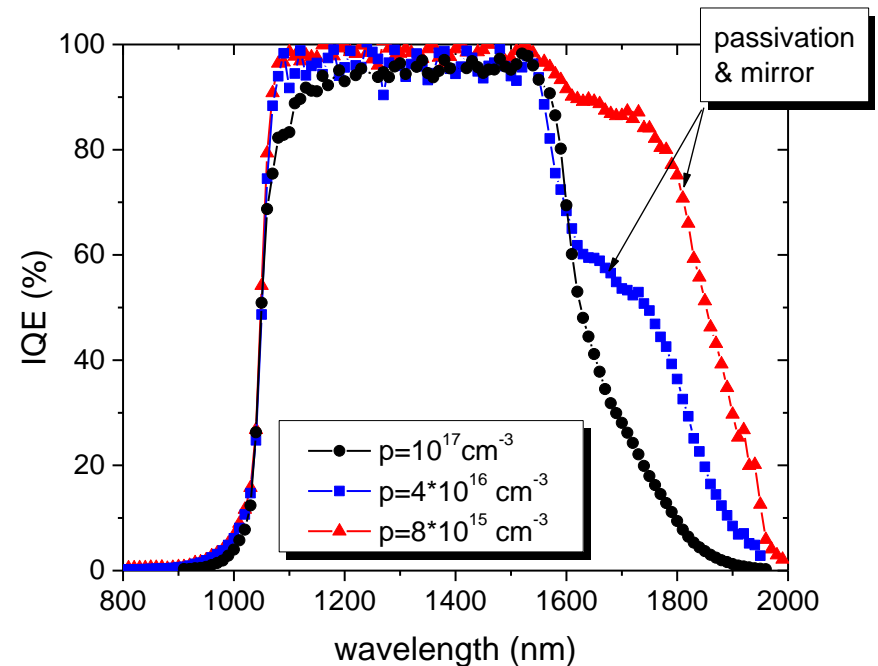


Motivation

III-V Multi-Junction Space Solar Cell

Project goals of SiLaSpaCe

- Decrease doping level of Ge
 - improve diffusion length
- Rear-side passivation ($a\text{-Si}_x\text{C}_{1-x}\text{:H}$) & Mirror layer ($a\text{-SiC:H}$)
 - increase overall current
 - reduce cell temperature



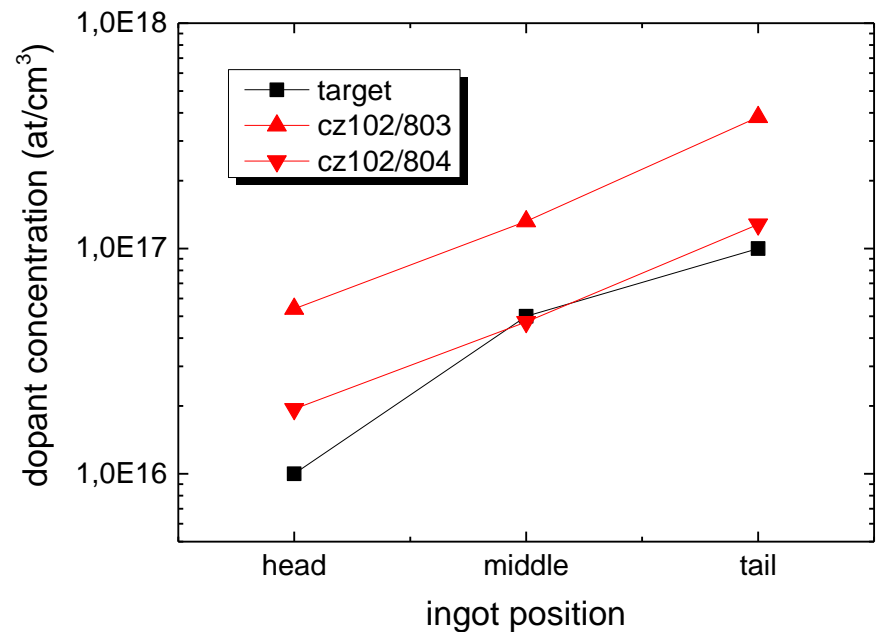
Content

- Fabrication of p-type Ge wafers with wide doping range
- Surface cleaning and passivation of Ge
- Accelerated aging with electrons

Germanium Wafer Fabrication

Crystallization with Dopant Gradient

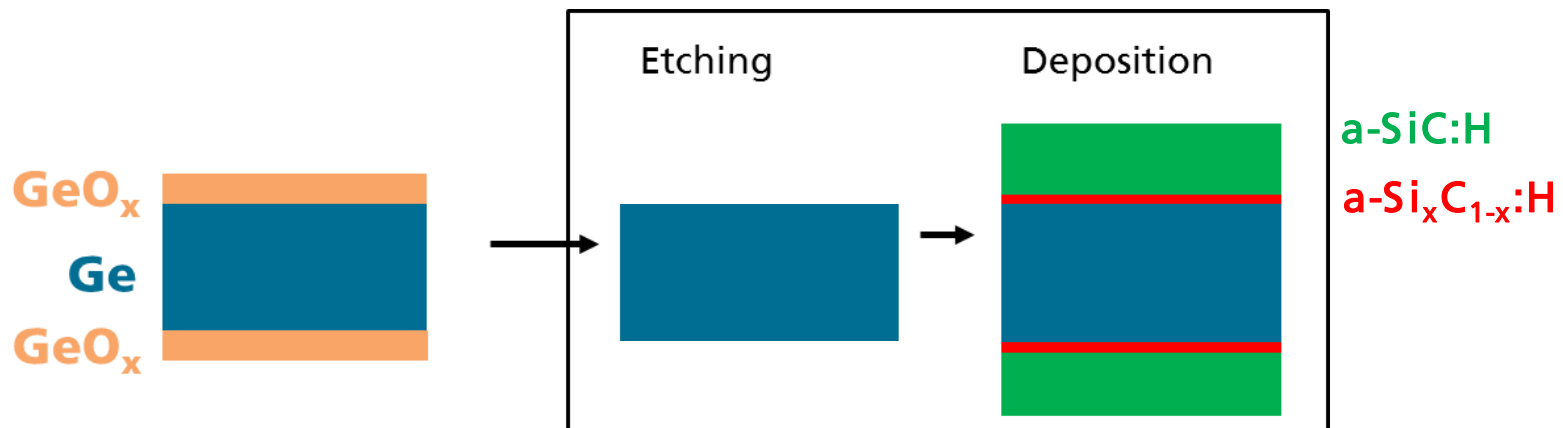
- Standard process for p-type:
 - constant Ga doping level in range of $10^{17} - 10^{18}$ at/cm³
- Doping gradient for project $1 \times 10^{16} - 1 \times 10^{17}$ at/cm³
- Coverage of whole doping range with 2 runs
- “high” $\approx 1 \times 10^{17}$ at/cm³
“middle” $\approx 6 \times 10^{16}$ at/cm³
“low” $\approx 2 \times 10^{16}$ at/cm³



Surface Passivation of Ge

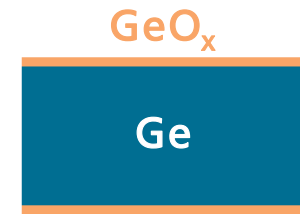
Preparation of "Lifetime" Samples

- Loading of samples "out-of-box"
- Plasma Enhanced Chemical Vapor Deposition / Etching (PECVD)
 - Gases: H_2 , Ar, SiH_4 , CH_4 (B_2H_6)
 - Temperature @ 270 °C

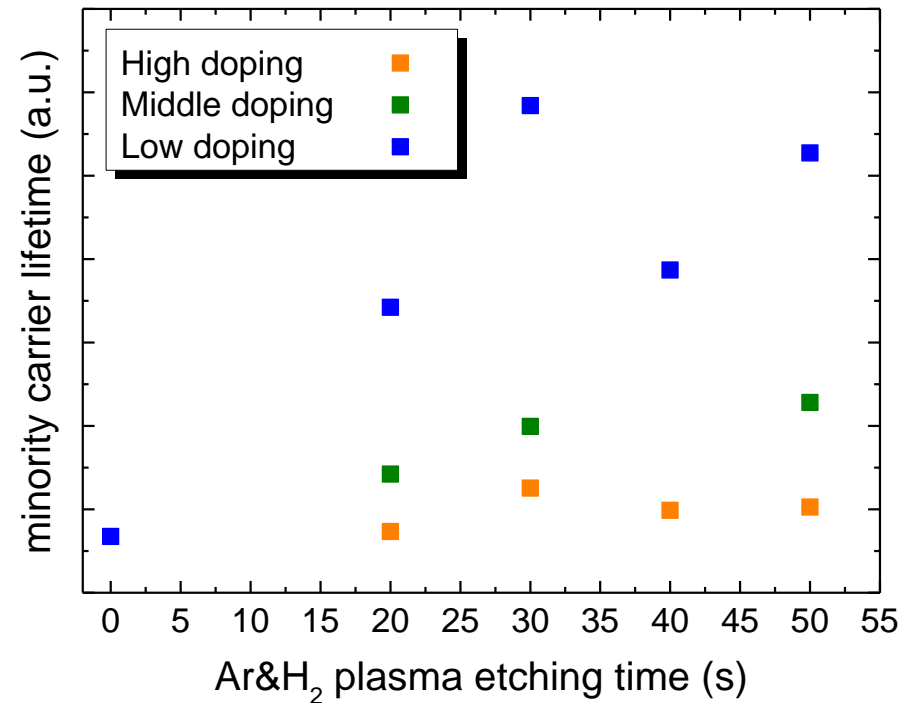


Surface Passivation of Ge

Plasma Etching of GeO_x



- Ar/ H_2 as etching gases
- Variation of etching time
- Deposition of $\text{a-Si}_x\text{C}_{1-x}:\text{H}$ layer
- Improvement up to 30 s
- No bulk damage?



Surface Passivation of Ge

Minority Carrier Lifetimes

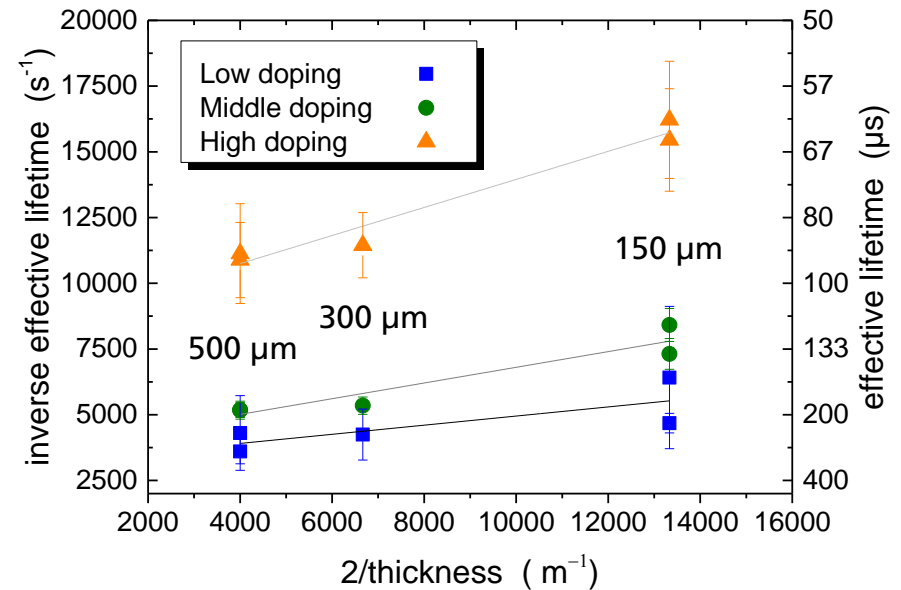
a-Si_xC_{1-x}:H

Ge

- Lifetime samples with $W = 150 \mu\text{m}, 300 \mu\text{m}$ and $500 \mu\text{m}$
- Extraction of τ_{bulk} and S_{eff}

$$\frac{1}{\tau_{eff}} = \frac{1}{\tau_{bulk}} + \frac{2}{W} \times S_{eff}$$

doping level	S_{eff} (cm/s)	τ_{bulk} (μs)
low	17	311
middle	30	262
high	53	116



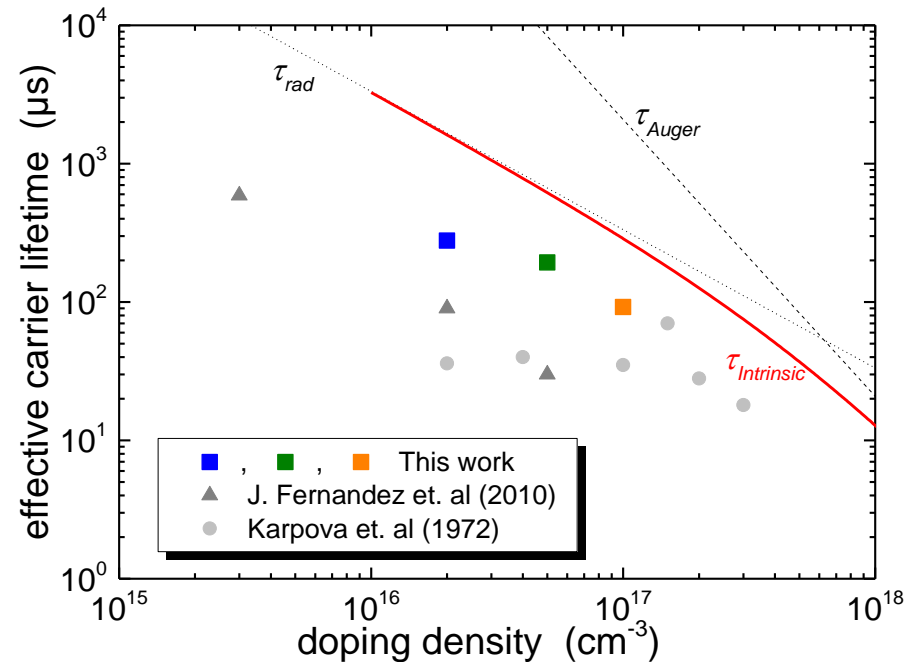
Surface Passivation of Ge

Minority Carrier Lifetimes

a-Si_xC_{1-x}:H

Ge

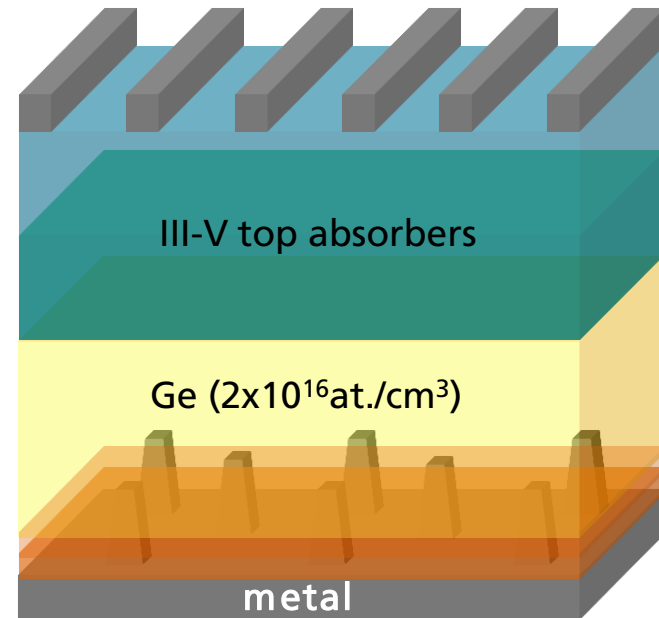
- τ_{eff} measured already close to theoretical limit
- Best reported values in this doping range



Surface Passivation of Ge

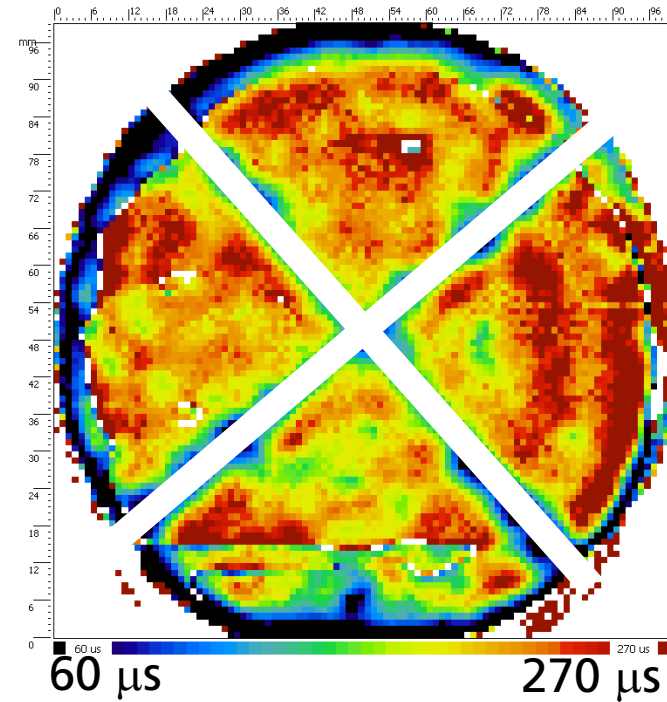
Thermal Annealing

- Motivation
 - Processes integration
 - Understanding of passivation mechanism
- Experiment:
 - Temp. = 400 °C – 500 °C
 - Time = 5 – 30 min
 - Laboratory atmosphere



Surface Passivation of Ge

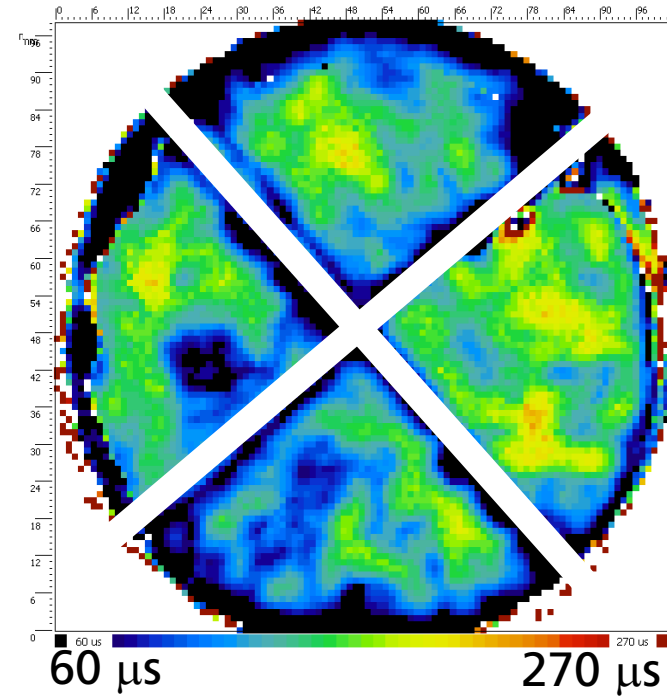
Thermal Annealing @ 500 °C



Surface Passivation of Ge

Thermal Annealing @ 500 °C

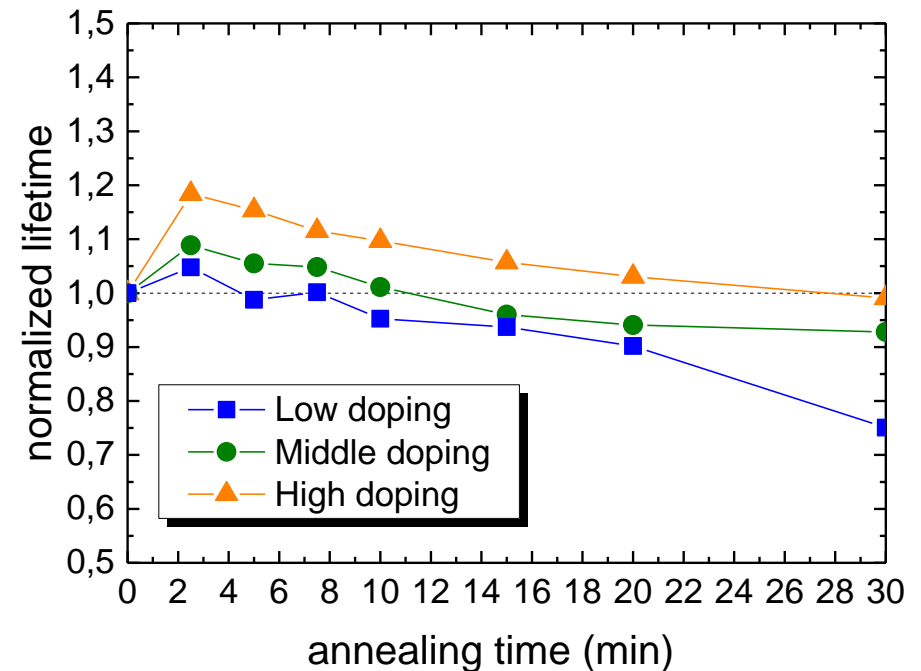
- 5 min leads to lifetime decrease of $\approx 100 \mu\text{s}$
- Blistering effects on surface visible
- ➔ Effusion of hydrogen



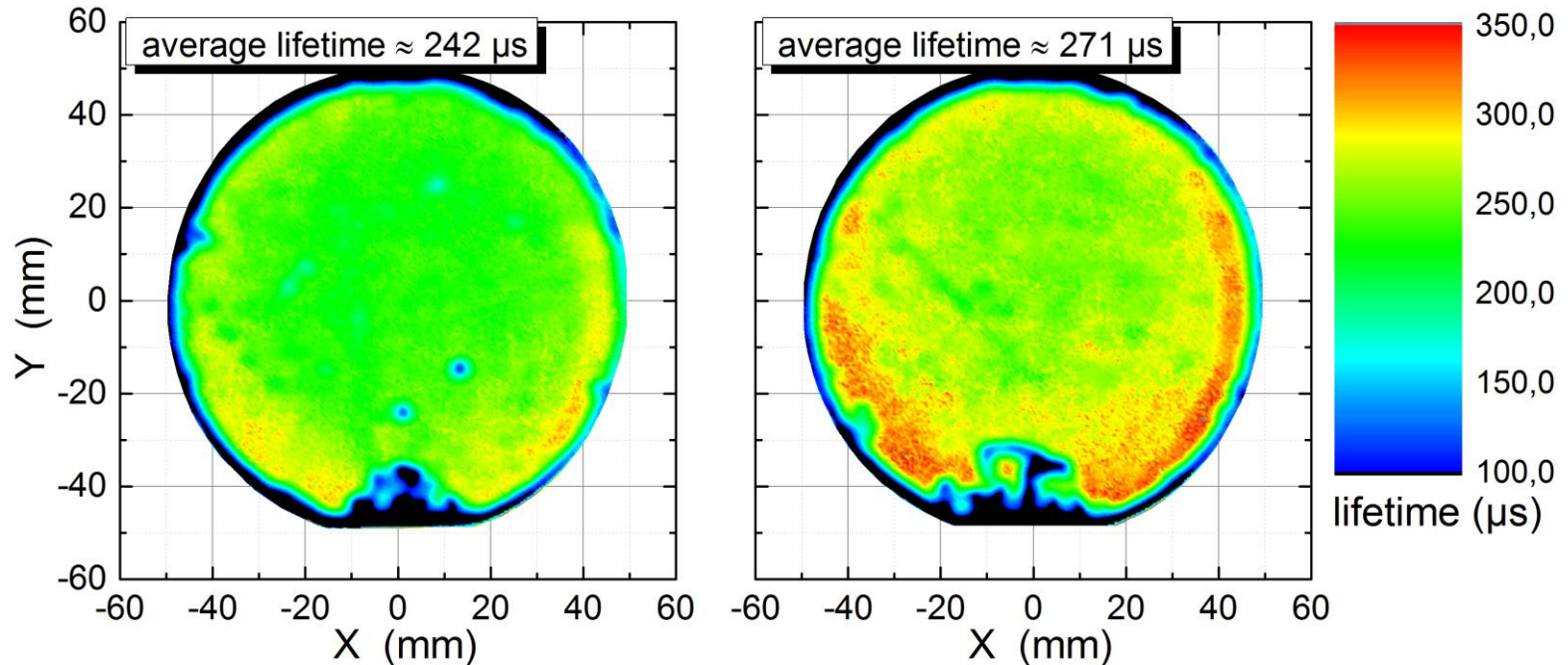
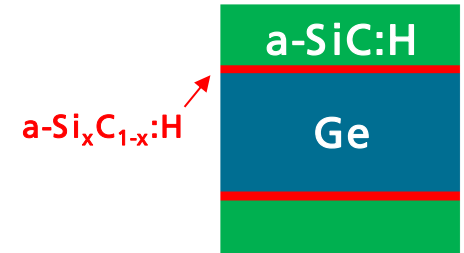
Surface Passivation of Ge

Thermal Annealing @ 400 °C

- $\leq 10-15$ min positive trend
- ➔ No degradation expected for contact annealing



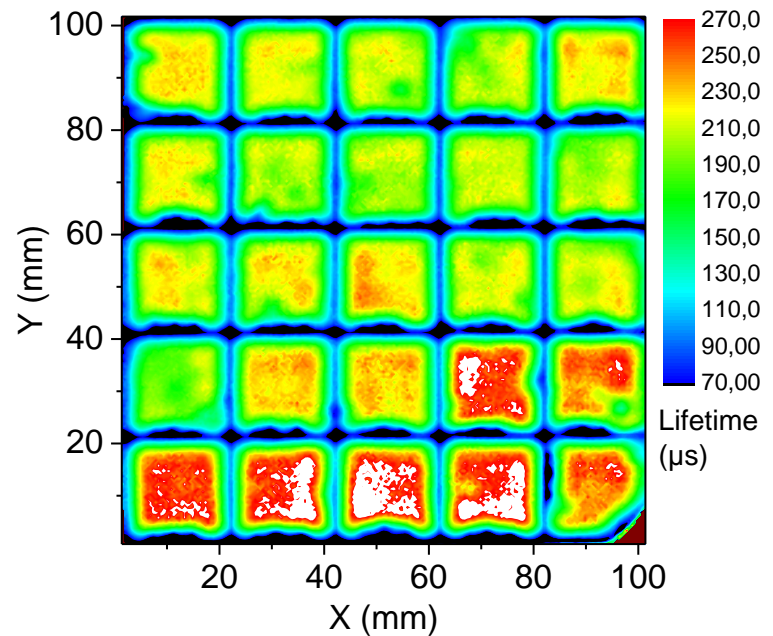
Surface Passivation of Ge Mirror Layer Deposition



- Deposition of SiC mirror layer (100 – 200 nm) + annealing
- ➔ Doped mirror layer leads to improved lifetimes

Accelerated Aging Electron Irradiation

- Motivation
 - Sufficient diffusion lengths after irradiation?
- > 100 samples prepared with variation of
 - Ge bulk doping
 - Mirror layer thickness
 - Mirror layer doping
 - Thermal annealing



total fluence
(e/cm^2)

3×10^{13}

10^{14}

3×10^{14}

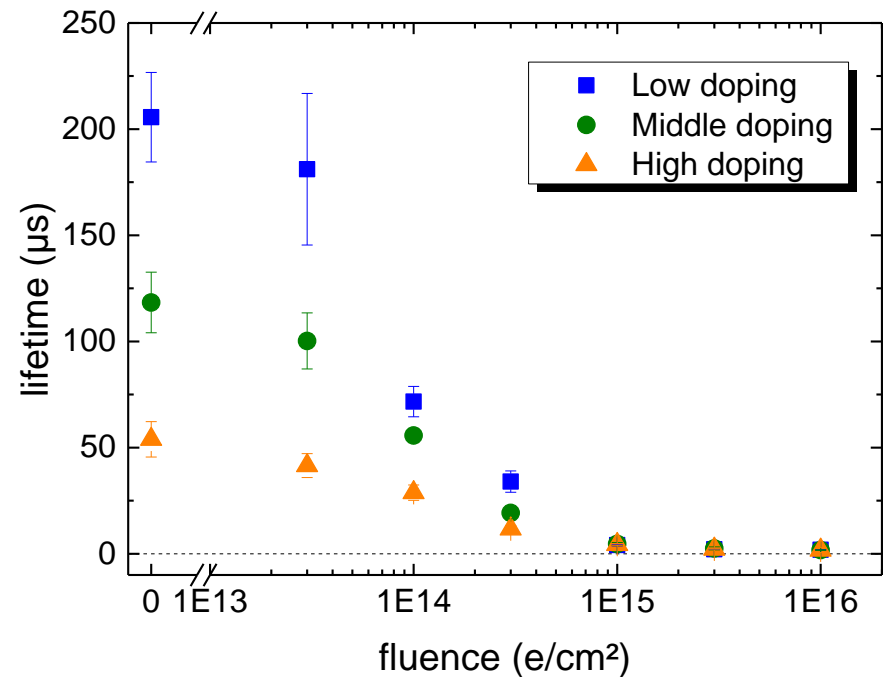
10^{15}

3×10^{15}

10^{16}

Accelerated Aging Electron Irradiation

- Strong degradation from 1×10^{14} e/cm² and higher
- All Ge samples reach similar level at 1×10^{15} e/cm²
- ➔ Realistic irradiation condition?
- ➔ Photon annealing?



Prince, M. B. (1953): Drift mobilities in semiconductors; Ge. In: *Phys. Rev.* 92 (3), S. 681–687.

Summary

- Plasma process for surface cleaning and passivation of Ge wafers works very well
- Thermal stability up to 400 °C
- Implementation of mirror layer successful
- Surface passivation effect not verified so far
- Electron irradiation effect mainly dependent on dopant level in Ge

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Thank you for your attention!

